

TACT SWITCH SPECIFICATION(轻触开关说明书)

1.	General specification	基本说明
	Contonal opcomication	- EXT VU /

1.1 Scope 范围 This specification covers the requirements for single key switches which have no keytop (TACT SWITCHES:MECHANICAL CONTACT). 此规范含盖单推柄和无推柄的轻触开关要求。

1.2 Operating Temperature Range 使用温度范围

-20 to 70 ℃(normal humidity, normal press).正常湿度,标准压力

1.3 Storage Temperature Rang 保存温度范围

-40 to 85 °C(normal humidity, normal press).

1.4 Test Conditions 测试条件

Tests and measurements shall be made in the following standard clnditions unless otherwise specified:

测试和计量按下列标准条件除非特殊说明

Normal temperature (temperature 5 to 35℃) 标准温度

Normal humidity (relative humidity 45 to 85%) 正常湿气

Normal pressure (pressure860 to 1060 mbars) 标准压力

In case any question arises from the judgement made, tests shall be conducted in the following conditions:

Temperature (20±2℃) 温度

Relative humidity (65±5%) 相对湿度

Pressure (860 to 1060 mbars) 压力

2. APPEARNCE, STYLE, AND DIMENSIONS 外形, 类型和尺寸

2.1 Appearance 外形

There shall be no defects that affect the serviceability of the product 外形必须无缺陷才不影响产品适用性

2.2 Style and Dimensions 类型和尺寸

Shall conform to the assembly drawings. 符合装配图

3. TYPE OF ACTUATION 动作类型

Tactile feedback 轻触返回

4. CONTACT ARRANGEMENT <u>1</u> poles <u>1</u> throws 接触形式 1 接点 1 回路

(Details of contact arrangement are given in the assembly drawings).

细接点形式在装配图中

5. MAXOMUM RATINGS DC <u>12</u> V <u>50</u> mA 最大额定值

6. MINOMUM RATINGS DC <u>1</u> V <u>10</u> μA 最小额定值

						APPD	CHKD	DSGD	TD 004VD 400
									TD-601XB 160g
									1/7
ZONE	SYMB	DATE	APPD	CHKD	DSGD				1/7

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6.2Mechanical 机械特性

Item 项 目			Test C	Requirements 规 格						
6.2.1.	Placing	the swite	ch such t	hat the di	irection o	f switch of	peration			
Actuating Force	vertical	and the	n gradua	lly increa	sing the	load app	lied to th	е		
动作力	center	of the ste	em, the m	160±30gf						
	come to	a stop s	hall be me							
	开关的动	作方向为	垂直放置开	新						
	测量的最	大负荷								
手感值	过回流	40%-60%								
6.2.2.	Placino	g the s	witch s	uch that	t the d	irection	of switc	h		
Travel	operat	ion is ve	ertical an	d then a	pplying	a static	oad twic	е		
行程	the ac	tuation 1	force to	the cent	ter of th	e stem,	the trave	el		
	distand	ce for	the sten	n to co	me to	a stop	shall b	e 0.15±0.05mm		
	measu	red.								
	开关的起	动作方向だ	为垂直放置	小						
	压力, 扌	生柄回到	自由位置的							
6.2.3.	The sa	ample sv	witch is i	nstalled	such th	at the d	irection o	of		
Return Force	switch	operation	on is ver	tical and	d, upon	depress	ion of th	,		
返回力	stem ii	n its cer	nter the v	30gf min						
	the ste	m to ret	urn to its							
	开关的表	动作方向	垂直放置牙							
	力,推	两回到自1	由位置时所							
6.2.4.	Placing	the swit	ch such t	hat the di	rection o	f switch c	peration	Thoro shall be no sign of		
Stop	vertical	, a static	load of 3	kgf sha	all be ap	olied in th	e directio	There shall be no sign of		
Strength	of stem	operation	on for a pe	damage mechanically and						
静止强度	开关的动	力作方向为	垂直放置	electrically 负 无机械的和电气的损伤迹象						
	荷,60	秒时间		之。 一 一 一 一 一 一 一 一 一 一 一 一 一 一 一 一 一 一 一						
6.2.5.	Placing	the swit	ch such t	is						
Stem	vertical	, the max	ximum foi	re						
Strength	to the c	lirection	of stem o	3 kgf						
推柄的强度	开关的动	力作方向为	7垂直放置	则						
	量到的晶	曼大承受力	J							
					APPD	CHKD	DSGD	TD-601XB 160g		
ZONE SYMB	DATE	APPD	CHKD	DSGD				2/7		
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6.PERFORMANCE 性能

6.1 Electrical 电气

Item 项 目	Test Condition 试验条件	Requirements 要求		
6.1.1. Contact Resistance 接触电阻	Applying a static load twice the actuating force to the center of the stem, measurements shall be made with a 1 kHz small-currentcontact resistance meter. 用两倍的动作力作静负载施加于按钮的中心,并用 1 千赫小电流接触电阻仪测量	<u>50</u> mΩmax.		
6.1.2. Insulation Resistance 绝缘电阻	Measurements shall be made following application of DC 100 V potintial across terminals and across terminals and frame for one minute. 在端子之间,端子与外壳之间施加 DC100V,一分种	<u>100</u> MΩmin		
6.1.3. Dielectric Witstanding voltage 电气耐压	AC250V (50Hz or 60Hz) shall be applied across terminals and across terminals and frame for one minute. 在端子与端子之间,端子与外壳之间施加 AC250V(50Hz or 60Hz)	There shall be mo breakdown 没有击穿		
6.1.4. Bounce 抖动	Lightly striking the center of the stem at a rate encountered in normal use (3 to 4 operations per sec), Bounce shall be tested at "ON" and "OFF" 在正常使用中(以每秒 3-4 次周期)轻轻地在手柄中心加力,在通与断瞬间测试抖动。	<u>20</u> m sec max .		
	TOFF* APP CHKD DSGD	TD-601XB 160g		

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6.3 Environmental 环境

Item 项 目	Test Condition 试验条件	Requirements 要求
6.3.1. Resistance to Low Temperatures 耐低温	Following the test set forth below the sample shall be left in mormal temperature and humidity conditions for one hour before measurements are made: 样品按下列条件进行耐低温试验,测试前在正常温度和湿度条例上放置 1 小时 (1) Temperature: -40±2℃ 温度 (2) Time: 96 hours 时间 (3) Water drops shall be removed 擦除水珠	Contact resistance: 200m Ω Max. 接触电阻 Insulation resistance: 50 M Ω Min. 绝缘电阻 Item 6.1 Item 6.2.1 Item 6.2.2
6.3.2. Heat Resistance 耐 热	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for one hour before measurements are made: 样品按下列条件进行耐热试验,测试前在正常温度和湿度条件下放置 1 小时 (1) Temperature:85±2℃ 温度 (2) Time: 96 hours 时间	Contact resistance: 200m Ω Max. 接触电阻 Insulation resistance: 50 M Ω Min. 绝缘电阻 Item 6.1 Item 6.2.1 Item 6.2.2
6.3.3. Moisture Resistance 耐潮湿	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for one hour before measurements are made: 样品按下列条件进行耐潮湿试验,测试前在正常温度和湿度条件下放置 1 小时(1) Temperature: 60±2°C 温度(2) Relative humidity: 90 to 95% 相对湿度(3) Time: 96 hours 时间(4) Water drops shall be removed 擦除水珠	Contact resistance: 200 m ohm max 接触电阻 Insulation resistance 50 M ohm min.绝缘电阻 Item 6.1 Item 6.2.1 Item 6.2.2
6.3.4. Temperature Cycling 温度循环	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for one hour before measurements are made. 样品按下列条件进行温度循环试验,测试前在正常温度和湿度条件下放置 1 小时 During this test, water drops shall be removed, 在试验期间,擦除水珠。 Cycling: 20 cycles 周期: 20 次	Contact resistance: 200 m ohm max 接触电阻 Insulation resistance 50 M ohm min.绝缘电阻 Item 6.1 Item 6.2.1 Item 6.2.2
	APPD CHKD DSGD	TD-601XB 160g
ZONE SYMB	DATE APPD CHKD DSGD	4/7

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6.4 Endurance	耐久特性									
Item 项 目		Те	st Cond	lition 试		Requirements 要求				
6.4.1. Operating Life 动作寿命	Measurer set forth b (1)DC 12 50mA 阻 (2)Rate o 动作频率: (3)Depres (4)Cycles 动作炎	below: V 50m 性负载 of oper :1-2 心 ssion: s of op	按下列统 nA resist 就 ation:1 t 次/每秒 240 gf	条件进行: ive load. o 2 oper 减压力	m Ir M A +	Contact resistance: 200 m Ω Max. 接触电阻 Insulation resistance: 50 M Ω Min. 绝缘电阻 Actuating force: 动作力 + 30 %or- 30%of initial force. ±30%初始动作力 Item 6.1.3 Item 6.2.2				
6.4.2. Vibration Resistance 耐振动	Vibration Resistance (4) Mode of sweep: Logarithmically sweep or (5) uniform sweep. 扫描周期: 10-55-10-Hz 约一分钟							Item 6.1 Item 6.2.1 Item 6.2.2		
6.4.3. Impact Shock Resistance 抗冲击	Measurer forth bel (1) Accele (2) Cycles (3) for a 试验次	low: 搜 eratior s of te total c	安下列条件 n:80g 加 st :3 cyc of 18cycl	⊧进行冲击 □速度 ≿les each	set	Item 6.1 Item 6.2.1 Item 6.2.2				
					APPD	CHKD	DSGI	D TD-601XB 160g		
ZONE SYMB	DATE A	\PPD	CHKD	DSGD				5/7		

			CTIN	NG .	SWITC	CH	SPEC	FICAT	ION
(1) Fol	i eguard t	he solde 进行焊接过 the swit	ering pr 过程中,7 ch asse	ocess,d 「可以用溶	序剂或类似 gainst flu	品清洗开	关		h a solvent or the like . opside.
(3) Ple	C	deliverin	g the g	oods at					ne is 90 days guaranty after
						APPD	CHKD	DSGD	TD-601XB 160g
ZONE	SYMB	DATE	APPD	CHKD	DSGD				6/7

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7.2 SWITCH HANDLING PRECAUTION 使用开关时注意事项

1. In case an automatic flow soldering apparatus is use for soldering.

用自动焊接设备焊接时应参照如下条件

原目								
PREHEAT TEMPERATURE 预热温度 PREHEAT TIME 预热温度 PREHEAT TIME 预热时间 PREHEAT TIME 预热时间 FLUX FOAMING 助焊剂浸泡 FLUX FOAMING DATE SOLDERIN BURN TEMPERATURE PRENTED FLUX FOAMING DATE FLUX MUST NOT BE APPLIED TO THAT SODE OF PRINTED CIRCUIT BOARD ON WHICH COMPONENTS ARE MOUNTED AND TO THE AREA WHIERE TERMINALS ARE LOCATED. DATE BURN TEMPERATURE PRENTED FROM THE PRENTED CIRCUIT BOARD ON WHICH COMPONENTS ARE MOUNTED AND TO THE AREA WHIERE TERMINALS ARE LOCATED. DATE BURN TEMPERATURE PRENTED FROM THE PRENTED CIRCUIT BOARD CIRCUIT BOARD CIRCUIT BOARD CIRCUIT BOARD FROM THE PRENTED CIRCUIT BOARD	ITEM	SOLDERING CONDITIONS						
PREHEAT TEMPERATURE 预热温度 PREHEAT TIME 预热温度 PREHEAT TIME 预热时间 TO SUCH AN EXTENT THAT FLUX WILL BE KEPT FLUSH WITH THE PRINTED CIRCUIT BOARD, TOP SURFACE ON WHICH COMPONENTS ARE MOUNTED.PRDPARATORY FLUX MUST NOT BE APPLIED TO THAT SODE OF PRINTED CIRCUIT BOARD ON WHICH COMPONENTS ARE MOUNTED AND TO THE AREA WHIERE TERMINALS ARE LOCATED. 助焊剂应涂在电路板上组装开关的印刷面上半部位,应防止助焊剂过量到电路板. SOLDERIN TEMPERATURE 焊锡温度 DURATION OF SOLDER IMMERSION 焊接时间 ALLOWABLE PREQUENCY ALLOWABLE PREQUENCY ALLOWABLE TIME AS SEC MAX ALLOWABLE TIMES MAX	项 目	焊接条件						
TEMPERATURE 预热温度 ON ITS SOLDERING SIDE) (电路板周围焊锡面的温度) PREHEAT TIME 预热时间 45 SEC MAX 45 W MAX TO SUCH AN EXTENT THAT FLUX WILL BE KEPT FLUSH WITH THE PRINTED CIRCUIT BOARDS, TOP SURFACE ON WHICH COMPONENTS ARE MOUNTED.PRDPARATORY FLUX MUST NOT BE APPLIED TO THAT SODE OF PRINTED CIRCUIT BOARD ON WHICH COMPONENTS ARE MOUNTED AND TO THE AREA WHIERE TERMINALS ARE LOCATED. 助焊剂应涂在电路板上组装开关的印刷面上半部位,应防止助焊剂过量到电路板. SOLDERIN TEMPERATURE 焊锡温度 DURATION OF SOLDER IMMERSION 焊接时间 ALLOWABLE PREQUENCY 2 TIMES MAX 2 M MAX		180°C MAX						
一		(AMBIENT TEMPERATURE OF PRINTED CIRCUIT BOARD						
度) PREHEAT TIME		ON ITS SOLDERING SIDE) (电路板周围焊锡面的温						
预热时间 TO SUCH AN EXTENT THAT FLUX WILL BE KEPT FLUSH WITH THE PRINTED CIRCUIT BOARDS, TOP SURFACE ON WHICH COMPONENTS ARE MOUNTED.PRDPARATORY FLUX MUST NOT BE APPLIED TO THAT SODE OF PRINTED CIRCUIT BOARD ON WHICH COMPONENTS ARE MOUNTED AND TO THE AREA WHIERE TERMINALS ARE LOCATED. 助焊剂应涂在电路板上组装开关的印刷面上半部位,应防止助焊剂过量到电路板. SOLDERIN TEMPERATURE 焊锡温度 DURATION OF SOLDER IMMERSION 焊接时间 ALLOWABLE PREQUENCY 25 MAX TIMES MAX TIMES MAX TO SUCH AN EXTENT THAT FLUX WILL BE KEPT FLUSH WILL		度)						
TO SUCH AN EXTENT THAT FLUX WILL BE KEPT FLUSH WITH THE PRINTED CIRCUIT BOARDS, TOP SURFACE ON WHICH COMPONENTS ARE MOUNTED.PRDPARATORY FLUX MUST NOT BE APPLIED TO THAT SODE OF PRINTED CIRCUIT BOARD ON WHICH COMPONENTS ARE MOUNTED AND TO THE AREA WHIERE TERMINALS ARE LOCATED. 助焊剂应涂在电路板上组装开关的印刷面上半部位,应防止助焊剂过量到电路板. SOLDERIN TEMPERATURE 焊锡温度 DURATION OF SOLDER IMMERSION 焊接时间 ALLOWABLE PREQUENCY TO SUCH AN EXTENT THAT FLUX WILL BE KEPT FLUSH WITH BOARDS, TOP SURFACE ON WHICH COMPONENTS ARE MOUNTED.PROPARATORY FLUX MUST NOT BE APPLIED TO THAT SODE OF PRINTED CIRCUIT BOARDS, TOP SURFACE ON WHICH COMPONENTS ARE MOUNTED.PROPARATORY FLUX MUST NOT BE APPLIED TO THAT SODE OF PRINTED CIRCUIT BOARDS, TOP SURFACE ON WHICH COMPONENTS ARE MOUNTED.PROPARATORY FLUX MILL BE KEPT FLUSH WITH BOARDS, TOP SURFACE ON WHICH COMPONENTS ARE MOUNTED.PROPARATORY FLUX MUST NOT BE APPLIED TO THAT SODE OF PRINTED CIRCUIT BOARDS, TOP SURFACE ON WHICH COMPONENTS ARE MOUNTED.PROPARATORY FLUX MUST NOT BE APPLIED TO THAT SODE OF PRINTED CIRCUIT BOARDS, TOP SURFACE ON WHICH COMPONENTS ARE MOUNTED.PROPARATORY FLUX MUST NOT BE APPLIED TO THAT SODE OF PRINTED CIRCUIT BOARDS, TOP SURFACE ON WHICH COMPONENTS ARE MOUNTED.PROPARATORY FLUX MUST NOT BE APPLIED TO THAT SODE OF PRINTED CIRCUIT BOARDS, TOP SUBJECT OF PRINTED CI	PREHEAT TIME	45 SEC MAX						
WITH THE PRINTED CIRCUIT BOARDS, TOP SURFACE ON WHICH COMPONENTS ARE MOUNTED.PRDPARATORY FLUX MUST NOT BE APPLIED TO THAT SODE OF PRINTED CIRCUIT BOARD ON WHICH COMPONENTS ARE MOUNTED AND TO THE AREA WHIERE TERMINALS ARE LOCATED. 助焊剂应涂在电路板上组装开关的印刷面上半部位,应防止助 焊剂过量到电路板. SOLDERIN TEMPERATURE 焊锡温度 DURATION OF SOLDER IMMERSION 焊接时间 ALLOWABLE PREQUENCY WITH THE PRINTED CIRCUIT BOARDS, TOP SURFACE ON WHICH COMPONENTS ARE MOUNTED.PRINTED THAT SODE OF PRINTED CIRCUIT BOARD OF PRINTED.	预热时间	45 秒 MAX						
TEMPERATURE 260°C MAX 焊锡温度 DURATION OF SOLDER IMMERSION F接时间 ALLOWABLE PREQUENCY 260°C MAX 5 SEC MAX 5 秋 MAX 27 MAX		WITH THE PRINTED CIRCUIT BOARDS,TOP SURFACE ON WHICH COMPONENTS ARE MOUNTED.PRDPARATORY FLUX MUST NOT BE APPLIED TO THAT SODE OF PRINTED CIRCUIT BOARD ON WHICH COMPONENTS ARE MOUNTED AND TO THE AREA WHIERE TERMINALS ARE LOCATED. 助焊剂应涂在电路板上组装开关的印刷面上半部位,应防止助						
TEMPERATURE 焊锡温度 DURATION OF SOLDER IMMERSION 焊接时间 ALLOWABLE PREQUENCY 260°C MAX 5 SEC MAX 5 秒 MAX 2 TIMES MAX	SOLDERIN	260°C MAY						
	TEMPERATURE							
SOLDER IMMERSION	焊锡温度	200 C IVIAX						
「MMERSION 5 秒 MAX 焊接时间 ALLOWABLE PREQUENCY 2 TIMES MAX 2 次 MAX	DURATION OF							
焊接时间 ALLOWABLE PREQUENCY 2 TIMES MAX 2 次 MAX	SOLDER	5 SEC MAX						
ALLOWABLE 2 TIMES MAX PREQUENCY 2 1/2 MAX	IMMERSION	5 秒 MAX						
PREQUENCY 2 TIMES MAX	焊接时间							
PREQUENCY 2 ½ MAX	ALLOWABLE	2 TIMES MAY						
允许重焊次数 2 次 WAX	PREQUENCY							
	允许重焊次数	2 次 MAX						

2. Other precautions 其他注意事项

(1) FOLLOWING THE SOLDERING PROCESS, DO NOT TRY TO CLEAN THE SWITCH SOLVENT OR THE LIKE.

进行焊接工艺时不应使用不整洁的东西对开关进行清洁。

(2) SAFEGUARD THE SWITCH ASSEMBLY AGAINST FLUX PENETRA TION FROM ITS TOP SIDE. 在组装开关时应防止助焊剂从开关的上部流入到开关内部。

						APPD	CHKD	DSGD	TD 601VD 160a
									TD-601XB 160g
									7/7
ZONE	SYMB	DATE	APPD	CHKD	DSGD				111